

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f877-20i-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

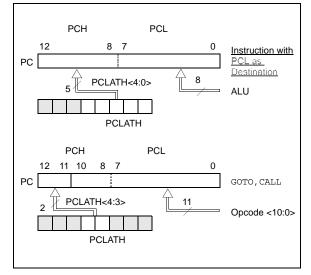
FIGURE 2-4: PIC16F874/873 REGISTER FILE MAP

,	File Address	A	File ddress	/	File Address		File Addres
Indirect addr. ^(*)	00h	Indirect addr.(*)	80h	Indirect addr.(*)	100h	Indirect addr.(*)	180h
TMR0	01h	OPTION_REG	81h	TMR0	101h	OPTION_REG	181h
PCL	02h	PCL	82h	PCL	102h	PCL	182h
STATUS	03h	STATUS	83h	STATUS	103h	STATUS	183h
FSR	04h	FSR	84h	FSR	104h	FSR	184h
PORTA	05h	TRISA	85h		105h		185h
PORTB	06h	TRISB	86h	PORTB	106h	TRISB	186h
PORTC	07h	TRISC	87h		107h		187h
PORTD ⁽¹⁾	08h	TRISD ⁽¹⁾	88h		108h		188h
PORTE ⁽¹⁾	09h	TRISE ⁽¹⁾	89h		109h		189h
PCLATH	0Ah	PCLATH	8Ah	PCLATH	10Ah	PCLATH	18Ah
INTCON	0Bh	INTCON	8Bh	INTCON	10Bh	INTCON	18Bh
PIR1	0Ch	PIE1	8Ch	EEDATA	10Ch	EECON1	18Cł
PIR2	0Dh	PIE2	8Dh	EEADR	10Dh	EECON2	18Dł
TMR1L	0Eh	PCON	8Eh	EEDATH	10Eh	Reserved ⁽²⁾	18Eh
TMR1H	0Fh		8Fh	EEADRH	10Fh	Reserved ⁽²⁾	18Fh
T1CON	10h		90h		110h		190h
TMR2	11h	SSPCON2	91h				
T2CON	12h	PR2	92h				
SSPBUF	13h	SSPADD	93h				
SSPCON	14h	SSPSTAT	94h				
CCPR1L	15h		95h				
CCPR1H	16h		96h				
CCP1CON	17h		97h				
RCSTA	18h	TXSTA	98h				
TXREG	19h	SPBRG	99h				
RCREG	1Ah		9Ah				
CCPR2L	1Bh		9Bh				
CCPR2H	1Ch		9Ch				
CCP2CON	1Dh		9Dh				
ADRESH	1Eh	ADRESL	9Eh				
ADCON0	1Fh	ADCON1	9Fh		1206		1A0h
	20h		A0h		120h		
General Purpose Register		General Purpose Register		accesses 20h-7Fh		accesses A0h - FFh	
96 Bytes		96 Bytes		2011 11 11	16Fh 170h		1EFt 1F0h
	754				1756		4
Bank 0	J 7Fh	Bank 1	FFh	Bank 2	17Fh	Bank 3	1FFł
* Not a Note 1: These	physical reg e registers	data memory locat gister. are not implemen are reserved, mai	ted on the	e PIC16F873.			

2.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any RESET, the upper bits of the PC will be cleared. Figure 2-5 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> \rightarrow PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> \rightarrow PCH).

FIGURE 2-5: LOADING OF PC IN DIFFERENT SITUATIONS



2.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, *"Implementing a Table Read"* (AN556).

2.3.2 STACK

The PIC16F87X family has an 8-level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed, or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

- **Note 1:** There are no status bits to indicate stack overflow or stack underflow conditions.
 - 2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

2.4 Program Memory Paging

All PIC16F87X devices are capable of addressing a continuous 8K word block of program memory. The CALL and GOTO instructions provide only 11 bits of address to allow branching within any 2K program memory page. When doing a CALL or GOTO instruction, the upper 2 bits of the address are provided by PCLATH<4:3>. When doing a CALL or GOTO instruction, the user must ensure that the page select bits are programmed so that the desired program memory page is addressed. If a return from a CALL instruction (or interrupt) is executed, the entire 13-bit PC is popped off the stack. Therefore, manipulation of the PCLATH<4:3> bits is not required for the return instructions (which POPs the address from the stack).

Note:	The contents of the PCLATH register are
	unchanged after a RETURN or RETFIE
	instruction is executed. The user must
	rewrite the contents of the PCLATH regis-
	ter for any subsequent subroutine calls or
	GOTO instructions.

Example 2-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that PCLATH is saved and restored by the Interrupt Service Routine (if interrupts are used).

EXAMPLE 2-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

	ORG 0x500 BCF PCLATH,4	
	BSF PCLATH, 3	;Select page 1 ;(800h-FFFh)
	CALL SUB1_P1 :	;Call subroutine in ;page 1 (800h-FFFh)
SUB1 P1	ORG 0x900	;page 1 (800h-FFFh)
SUB1_P1	:	;called subroutine ;page 1 (800h-FFFh)
	: RETURN	;return to ;Call subroutine ;in page 0 ;(000h-7FFh)

Name	Bit#	Buffer	Function
RB0/INT	bit0	TTL/ST ⁽¹⁾	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3/PGM ⁽³⁾	bit3	TTL	Input/output pin or programming pin in LVP mode. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt-on-change). Internal software programmable weak pull-up.
RB6/PGC	bit6	TTL/ST ⁽²⁾	Input/output pin (with interrupt-on-change) or In-Circuit Debugger pin. Internal software programmable weak pull-up. Serial programming clock.
RB7/PGD	bit7	TTL/ST ⁽²⁾	Input/output pin (with interrupt-on-change) or In-Circuit Debugger pin. Internal software programmable weak pull-up. Serial programming data.

TABLE 3-3: PORTB FUNCTIONS

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

3: Low Voltage ICSP Programming (LVP) is enabled by default, which disables the RB3 I/O function. LVP must be disabled to enable RB3 as an I/O pin and allow maximum compatibility to the other 28-pin and 40-pin mid-range devices.

TABLE 3-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
06h, 106h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	XXXX XXXX	uuuu uuuu
86h, 186h	TRISB	PORTB	PORTB Data Direction Register								1111 1111
81h, 181h	OPTION_REG	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

4.9 FLASH Program Memory Write Protection

The configuration word contains a bit that write protects the FLASH program memory, called WRT. This bit can only be accessed when programming the PIC16F87X device via ICSP. Once write protection is enabled, only an erase of the entire device will disable it. When enabled, write protection prevents any writes to FLASH program memory. Write protection does not affect program memory reads.

TABLE 4-1: READ/WRITE STATE OF INTERNAL FLASH PROGRAM MEMORY

Со	nfiguration	Bits	Manageral	Internal	Internal		
CP1	CP0	WRT	Memory Location	Read	Write	ICSP Read	ICSP Write
0	0	x	All program memory	Yes	No	No	No
0	1	0	Unprotected areas	Yes	No	Yes	No
0	1	0	Protected areas	Yes	No	No	No
0	1	1	Unprotected areas	Yes	Yes	Yes	No
0	1	1	Protected areas	Yes	No	No	No
1	0	0	Unprotected areas	Yes	No	Yes	No
1	0	0	Protected areas	Yes	No	No	No
1	0	1	Unprotected areas	Yes	Yes	Yes	No
1	0	1	Protected areas	Yes	No	No	No
1	1	0	All program memory	Yes	No	Yes	Yes
1	1	1	All program memory	Yes	Yes	Yes	Yes

TABLE 4-2:	REGISTERS ASSOCIATED WITH DATA EEPROM/PROGRAM FLASH

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh, 18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
10Dh	EEADR	EEPRON	Address	s Register	, Low Byt	е				xxxx xxxx	uuuu uuuu
10Fh	EEADRH	—	—	—	EEPRON	Address,	High Byte)		xxxx xxxx	uuuu uuuu
10Ch	EEDATA	EEPRON	l Data Re	egister, Lo	w Byte					xxxx xxxx	uuuu uuuu
10Eh	EEDATH	—	—	EEPRO	M Data Re	egister, Hig	h Byte			xxxx xxxx	uuuu uuuu
18Ch	EECON1	EEPGD	_	_	—	WRERR	WREN	WR	RD	x x000	x u000
18Dh	EECON2	EEPRON	I Control	_	_						
8Dh	PIE2	—	(1)	- EEIE BCLIE - CCP2IE						-r-0 00	-r-0 00
0Dh	PIR2	_	(1)	_	EEIF	BCLIF	_	_	CCP2IF	-r-0 00	-r-0 00

Legend: x = unknown, u = unchanged, r = reserved, - = unimplemented, read as '0'. Shaded cells are not used during FLASH/EEPROM access.

Note 1: These bits are reserved; always maintain these bits clear.

8.0 CAPTURE/COMPARE/PWM MODULES

Each Capture/Compare/PWM (CCP) module contains a 16-bit register which can operate as a:

- 16-bit Capture register
- 16-bit Compare register
- PWM Master/Slave Duty Cycle register

Both the CCP1 and CCP2 modules are identical in operation, with the exception being the operation of the special event trigger. Table 8-1 and Table 8-2 show the resources and interactions of the CCP module(s). In the following sections, the operation of a CCP module is described with respect to CCP1. CCP2 operates the same as CCP1, except where noted.

CCP1 Module:

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. The special event trigger is generated by a compare match and will reset Timer1.

CCP2 Module:

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. The special event trigger is generated by a compare match and will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Additional information on CCP modules is available in the PIC[®] MCU Mid-Range Family Reference Manual (DS33023) and in application note AN594, "Using the CCP Modules" (DS00594).

TABLE 8-1: CCP MODE - TIMER RESOURCES REQUIRED

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 8-2:INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1
PWM	PWM	The PWMs will have the same frequency and update rate (TMR2 interrupt)
PWM	Capture	None
PWM	Compare	None

9.1.2 SLAVE MODE

In Slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched, the interrupt flag bit SSPIF (PIR1<3>) is set.

While in Slave mode, the external clock is supplied by the external clock source on the SCK pin. This external clock must meet the minimum high and low times as specified in the electrical specifications. While in SLEEP mode, the slave can transmit/receive data. When a byte is received, the device will wake-up from SLEEP.

- Note 1: When the <u>SPI</u> module is in Slave mode with <u>SS</u> pin control enabled (SSPCON<3:0> = 0100), the SPI module will reset if the <u>SS</u> pin is set to VDD.
 - 2: If the SPI is used in Slave mode with CKE = '1', then SS pin control must be enabled.

SCK (CKP = 0) SCK (CKP = 1) SD0 SD0 SD1 (SMP = 0) B17 SD1 SD1

FIGURE 9-3: SPI MODE TIMING (SLAVE MODE WITH CKE = 0)



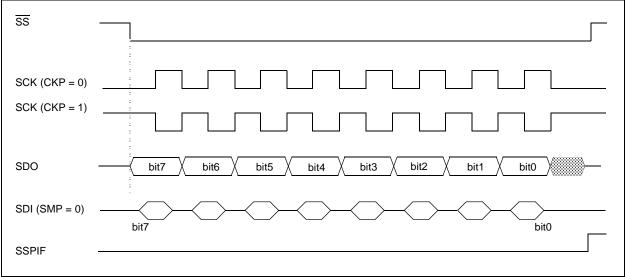


TABLE 9-1: REGISTERS ASSOCIATED WITH SPI OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on: MCLR, WDT
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchrono	ous Serial	Port Recei	ve Buff	er/Transm	it Register			xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP	CKE	D/A	Р	S	R/W	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the SSP in SPI mode. **Note 1:** These bits are reserved on PCI16F873/876 devices; always maintain these bits clear.

10.2 USART Asynchronous Mode

In this mode, the USART uses standard non-return-tozero (NRZ) format (one START bit, eight or nine data bits, and one STOP bit). The most common data format is 8-bits. An on-chip, dedicated, 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The transmitter and receiver are functionally independent, but use the same data format and baud rate. The baud rate generator produces a clock, either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- · Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

10.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 10-1. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the STOP bit has been transmitted from the previous load. As soon as the STOP bit is transmitted, the TSR is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one TCY), the TXREG register is empty and flag bit TXIF (PIR1<4>) is set. This interrupt can be

enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set, regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit TRMT (TXSTA<1>) shows the status of the TSR register. Status bit TRMT is a read only bit, which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty.

- **Note 1:** The TSR register is not mapped in data memory, so it is not available to the user.
 - 2: Flag bit TXIF is set when enable bit TXEN is set. TXIF is cleared by loading TXREG.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 10-2). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally, when transmission is first started, the TSR register is empty. At that point, transfer to the TXREG register will result in an immediate transfer to TSR, resulting in an empty TXREG. A back-to-back transfer is thus possible (Figure 10-3). Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. As a result, the RC6/TX/CK pin will revert to hi-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit may be loaded in the TSR register.

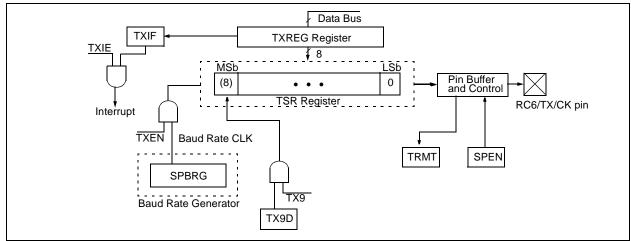
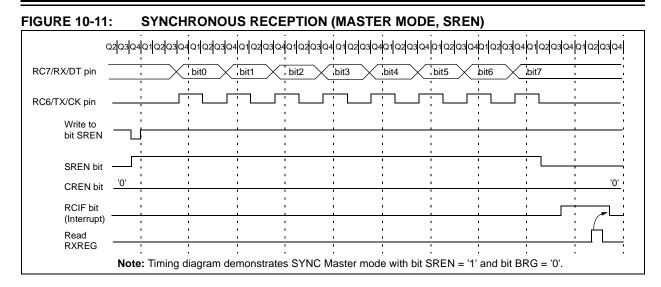


FIGURE 10-1: USART TRANSMIT BLOCK DIAGRAM

PIC16F87X



10.4 USART Synchronous Slave Mode

Synchronous Slave mode differs from the Master mode in the fact that the shift clock is supplied externally at the RC6/TX/CK pin (instead of being supplied internally in Master mode). This allows the device to transfer or receive data while in SLEEP mode. Slave mode is entered by clearing bit CSRC (TXSTA<7>).

10.4.1 USART SYNCHRONOUS SLAVE TRANSMIT

The operation of the Synchronous Master and Slave modes is identical, except in the case of the SLEEP mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

- a) The first word will immediately transfer to the TSR register and transmit.
- b) The second word will remain in TXREG register.
- c) Flag bit TXIF will not be set.
- d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit TXIF will now be set.

e) If enable bit TXIE is set, the interrupt will wake the chip from SLEEP and if the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

When setting up a Synchronous Slave Transmission, follow these steps:

- 1. Enable the synchronous slave serial port by setting bits SYNC and SPEN and clearing bit CSRC.
- 2. Clear bits CREN and SREN.
- 3. If interrupts are desired, then set enable bit TXIE.
- 4. If 9-bit transmission is desired, then set bit TX9.
- 5. Enable the transmission by setting enable bit TXEN.
- 6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
- 7. Start transmission by loading data to the TXREG register.
- 8. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 10-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	R0IF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	x000 0000
19h	TXREG	USART Tr	USART Transmit Register						0000 0000	0000 0000	
8Ch	PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register					0000 0000	0000 0000			

Legend: x = unknown, - = unimplemented, read as '0'. Shaded cells are not used for synchronous slave transmission. Note 1: Bits PSPIE and PSPIF are reserved on PIC16F873/876 devices; always maintain these bits clear. These steps should be followed for doing an A/D Conversion:

- 1. Configure the A/D module:
 - Configure analog pins/voltage reference and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D conversion clock (ADCON0)
 - Turn on A/D module (ADCON0)
- 2. Configure A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set PEIE bit
 - Set GIE bit

- 3. Wait the required acquisition time.
- 4. Start conversion:
 Set GO/DONE bit (ADCON0)
- 5. Wait for A/D conversion to complete, by either:
 - Polling for the GO/DONE bit to be cleared (with interrupts enabled); OR
 - Waiting for the A/D interrupt
- 6. Read A/D result register pair (ADRESH:ADRESL), clear bit ADIF if required.
- For the next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before the next acquisition starts.

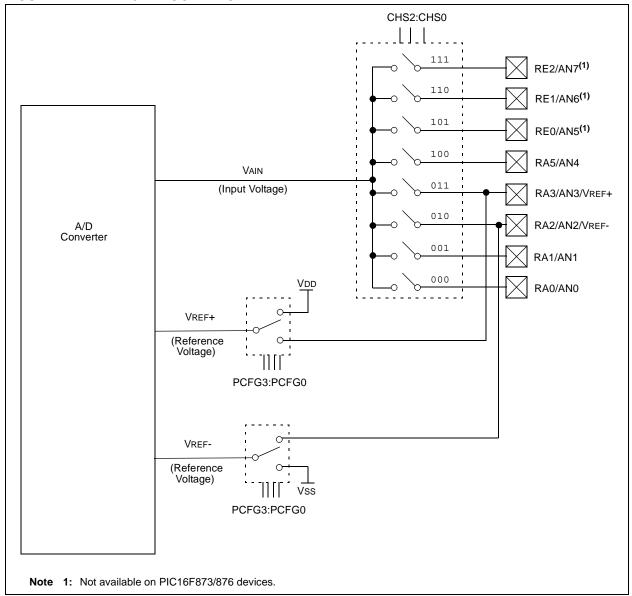


FIGURE 11-1: A/D BLOCK DIAGRAM

11.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 11-2. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD), see Figure 11-2. The maximum recommended impedance for analog sources is 10 k Ω . As the impedance is decreased, the acquisition time may be decreased.

EQUATION 11-1: ACQUISITION TIME

After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 11-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

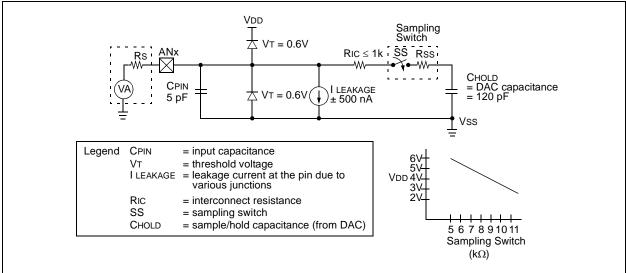
To calculate the minimum acquisition time, TACQ, see the $PIC^{\textcircled{R}}$ MCU Mid-Range Reference Manual (DS33023).

TACQ	= Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient
	= TAMP + TC + TCOFF
	$= 2\mu s + TC + [(Temperature -25^{\circ}C)(0.05\mu s/^{\circ}C)]$
TC	= CHOLD (RIC + RSS + RS) $In(1/2047)$
	= $-120 \text{pF} (1 \text{k}\Omega + 7 \text{k}\Omega + 10 \text{k}\Omega) \ln(0.0004885)$
	$= 16.47 \mu s$
TACQ	= $2\mu s + 16.47\mu s + [(50^{\circ}C - 25^{\circ}C)(0.05\mu s/^{\circ}C)]$
	$= 19.72 \mu s$
L	

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

- **2:** The charge holding capacitor (CHOLD) is not discharged after each conversion.
- **3:** The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.
- **4:** After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time, the holding capacitor is not connected to the selected A/D input channel.

FIGURE 11-2: ANALOG INPUT MODEL



12.3 **RESET**

The PIC16F87X differentiates between various kinds of RESET:

- Power-on Reset (POR)
- MCLR Reset during normal operation
- MCLR Reset during SLEEP
- WDT Reset (during normal operation)
- WDT Wake-up (during SLEEP)
- Brown-out Reset (BOR)

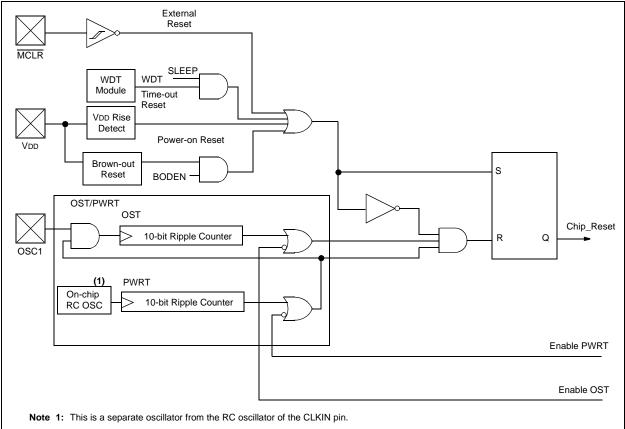
Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-on Reset (POR), on the MCLR and WDT Reset, on MCLR Reset during SLEEP, and Brown-out Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different RESET situations as indicated in Table 12-4. These bits are used in software to determine the nature of the RESET. See Table 12-6 for a full description of RESET states of all registers.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 12-4.

These devices have a MCLR noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{\text{MCLR}}$ pin low.





PIC16F87X



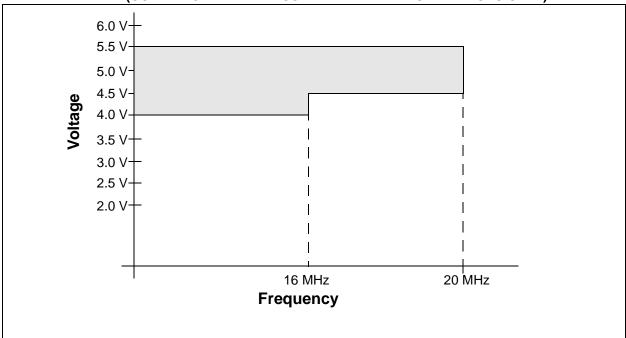
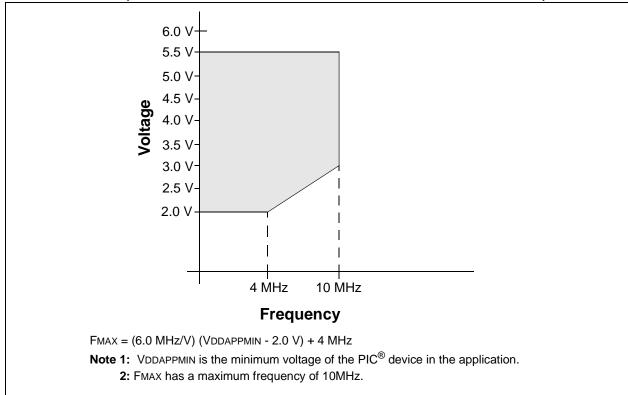


FIGURE 15-2: PIC16LF87X-04 VOLTAGE-FREQUENCY GRAPH (COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES ONLY)





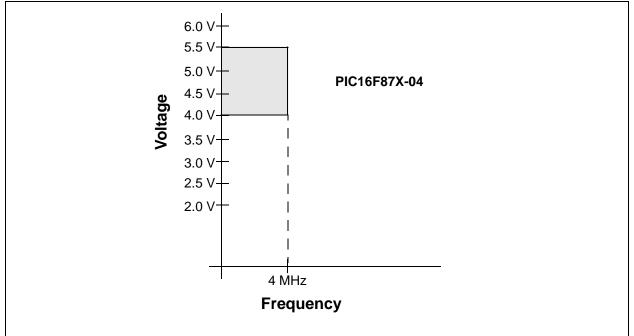
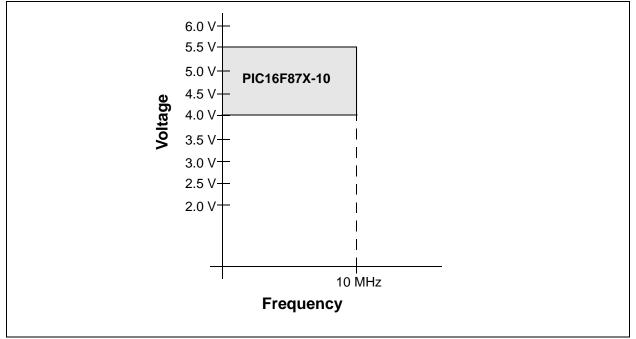


FIGURE 15-4: PIC16F87X-10 VOLTAGE-FREQUENCY GRAPH (EXTENDED TEMPERATURE RANGE ONLY)



15.2 DC Characteristics: PIC16F873/874/876/877-04 (Commercial, Industrial) PIC16F873/874/876/877-20 (Commercial, Industrial) PIC16LF873/874/876/877-04 (Commercial, Industrial) (Continued)

DC CHA	$\begin{array}{llllllllllllllllllllllllllllllllllll$						
Param No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
	Vol	Output Low Voltage					
D080		I/O ports			0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083		OSC2/CLKOUT (RC osc config)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	Voн	Output High Voltage					
D090		I/O ports ⁽³⁾	Vdd - 0.7			V	Юн = -3.0 mA, VDD = 4.5V, -40°С to +85°С
D092		OSC2/CLKOUT (RC osc config)	Vdd - 0.7	_	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С
D150*	Vod	Open-Drain High Voltage		_	8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	Cosc2	OSC2 pin	_		15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	Cio	All I/O pins and OSC2 (RC mode)	_	—	50	pF	
D102	Св	SCL, SDA (I ² C mode)		_	400	pF	
		Data EEPROM Memory					
D120	ED	Endurance	100K	—	—		25°C at 5V
D121	Vdrw	VDD for read/write	Vmin	—	5.5	V	Using EECON to read/write VMIN = min. operating voltage
D122	TDEW	Erase/write cycle time		4	8	ms	
		Program FLASH Memory					
D130	Eр	Endurance	1000	—	—		25°C at 5V
D131	Vpr	VDD for read	Vmin	—	5.5	V	VMIN = min operating voltage
D132A		VDD for erase/write	Vmin	—	5.5	V	Using EECON to read/write, VMIN = min. operating voltage
D133		Erase/Write cycle time		4	8	ms	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16F87X be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

15.4 DC Characteristics: PIC16F873/874/876/877-04 (Extended) PIC16F873/874/876/877-10 (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ Operating voltage VDD range as described in DC specification (Section 15.1)						
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions		
	VIL	Input Low Voltage							
		I/O ports							
D030		with TTL buffer	Vss	—	0.15Vdd		For entire VDD range		
D030A			Vss	—	0.8V	V	$4.5V \leq V\text{DD} \leq 5.5V$		
D031		with Schmitt Trigger buffer	Vss	—	0.2Vdd	V			
D032		MCLR, OSC1 (in RC mode)	Vss	—	0.2Vdd	V			
D033		OSC1 (in XT, HS and LP)	Vss	—	0.3Vdd	V	(Note 1)		
		Ports RC3 and RC4							
D034		with Schmitt Trigger buffer	Vss	—	0.3Vdd	V	For entire VDD range		
D034A		with SMBus	-0.5	—	0.6	V	for $VDD = 4.5$ to $5.5V$		
	Vih	Input High Voltage							
		I/O ports		—					
D040		with TTL buffer	2.0	—	Vdd	V	$4.5V \leq V\text{DD} \leq 5.5V$		
D040A			0.25Vdd	—	Vdd	V	For entire VDD range		
			+ 0.8V						
D041		with Schmitt Trigger buffer	0.8Vdd	—	Vdd	V	For entire VDD range		
D042		MCLR	0.8Vdd	—	Vdd	V			
D042A		OSC1 (XT, HS and LP)	0.7Vdd	—	Vdd	V	(Note 1)		
D043		OSC1 (in RC mode)	0.9Vdd	—	Vdd	V			
		Ports RC3 and RC4							
D044		with Schmitt Trigger buffer	0.7VDD	—	Vdd	V	For entire VDD range		
D044A		with SMBus	1.4	—	5.5	V	for VDD = 4.5 to 5.5V		
D070A	IPURB		50	250	400	μA	VDD = 5V, VPIN = VSS,		
	lı∟	Input Leakage Current ^(2, 3)							
D060		I/O ports	-	-	±1	μΑ	$Vss \le VPIN \le VDD,$		
							Pin at hi-impedance		
D061		MCLR, RA4/T0CKI	-	-	±5	μΑ	$Vss \leq V \text{PIN} \leq V \text{DD}$		
D063		OSC1	-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP osc configuration		

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16F87X be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

PIC16F87X

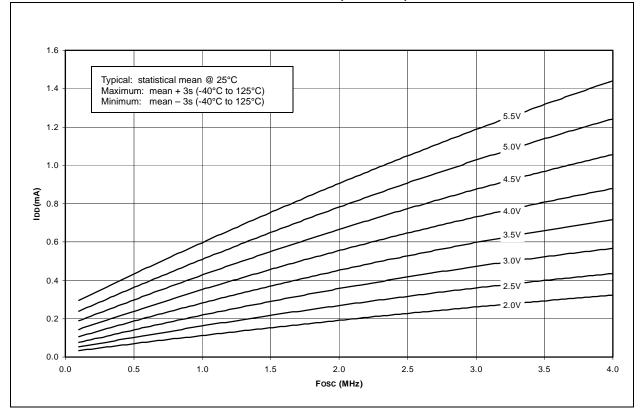
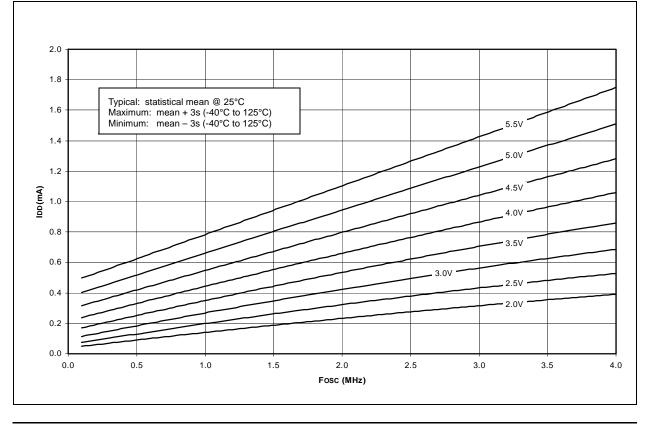


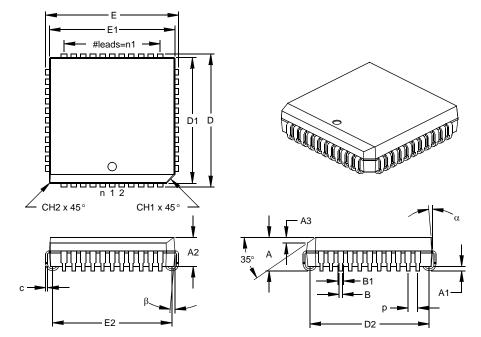
FIGURE 16-3: TYPICAL IDD vs. Fosc OVER VDD (XT MODE)





44-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES*		MILLIMETERS			
Dimension	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		44			44	
Pitch	р		.050			1.27	
Pins per Side	n1		11			11	
Overall Height	А	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	Е	.685	.690	.695	17.40	17.53	17.65
Overall Length	D	.685	.690	.695	17.40	17.53	17.65
Molded Package Width	E1	.650	.653	.656	16.51	16.59	16.66
Molded Package Length	D1	.650	.653	.656	16.51	16.59	16.66
Footprint Width	E2	.590	.620	.630	14.99	15.75	16.00
Footprint Length	D2	.590	.620	.630	14.99	15.75	16.00
Lead Thickness	С	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	В	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-047

Drawing No. C04-048

APPENDIX C: CONVERSION CONSIDERATIONS

Considerations for converting from previous versions of devices to the ones listed in this data sheet are listed in Table C-1.

TABLE C-1:	CONVERSION
	CONSIDERATIONS

Characteristic	PIC16C7X	PIC16F87X		
Pins	28/40	28/40		
Timers	3	3		
Interrupts	11 or 12	13 or 14		
Communication	PSP, USART, SSP (SPI, I ² C Slave)	PSP, USART, SSP (SPI, I ² C Master/Slave)		
Frequency	20 MHz	20 MHz		
Voltage	2.5V - 5.5V	2.0V - 5.5V		
A/D	8-bit	10-bit		
CCP	2	2		
Program Memory	4K, 8K EPROM	4K, 8K FLASH		
RAM	192, 368 bytes	192, 368 bytes		
EEPROM data	None	128, 256 bytes		
Other	_	In-Circuit Debugger, Low Voltage Programming		

W

Wake-up from SLEEP 119, 132
Interrupts 125, 126
MCLR Reset126
Timing Diagram133
WDT Reset 126
Watchdog Timer (WDT) 119, 131
Block Diagram131
Enable (WDTE Bit)131
Postscaler. See Postscaler, WDT
Programming Considerations131
RC Oscillator131
Time-out Period131
WDT Reset, Normal Operation 123, 125, 126
WDT Reset, SLEEP 123, 125, 126
Waveform for General Call Address Sequence
WCOL
WCOL Status Flag80
Write Collision Detect bit, WCOL67
Write Verify
Data EEPROM and FLASH Program Memory45
WWW, On-Line Support4